# Display Elektronik GmbH

# DATA SHEET

# **TFT MODULE**

# **DEM 4801280A VMH-PW-N**

6,8" TFT

**Product Specification** 

Ver.: 0

# **Revision History**

Revision	Date	Originator	Detail	Remarks
0	18.01.2017	MH	Initial Release	-

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# 1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver Ics and a backlight unit.

#### 2. Module Parameter

Features	Details	Unit
Display Size (Diagonal)	6.8"	-
LCD Type	IPS TFT	-
Display Mode	Transmissive / Normally black	-
Resolution	480 x RGB x 1280	Pixels
View Direction	FULL VIEW	Best Image
Module Outline	66.12 x 171.79 x 2.50 (Note1 )	mm
Active Area	60.22 x 160.59	mm
Pixel Size	0.12546 x 0.12546	mm
Pixel Arrangement	Stripe	-
Display Colors	16.7 Million	-
Interface	MIPI	-
With or without touch panel	Without	-
Driver IC	EK79030	-
Operating Temperature	-20°C to +60°C	°C
Storage Temperature	-20°C to +65°C	°C
Weight	t.b.d.	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

# 3. Absolute Maximum Ratings

Vss=0V, Ta=25°C

Item	Symbol	Min.	Max.	Unit
Supply Voltage	VCI	2.5	6.0	V
Supply Voltage	IOVCC	1.8	5.5	
Storage Temperature	T <sub>STG</sub>	-20	+65	°C
Operating Temperature	Top	-20	+60	°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over 50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10°C, and the back ground will become darker at high temperature operating.

# 4. DC Characteristics

Item	Symbol	Min.	Тур.	Max.	Unit	
Supply Voltage	VCI	2.5	3.3	3.6	V	
Supply Voltage	IOVCC	1.8	3.3	3.6		
VDDIO Input Low Level Vo	VIL	VSS	-	0.2*IOVCC	mV	
VDDIO Input High Level Voltage		V <sub>IH</sub>	0.8*IOVCC	-	IOVCC	mV
Current Consumption Logic		ICC+ IIN	_	t.b.d.	_	mA
All Black	Analog	ICC+ IIIV		i.b.u.	_	шА

# 5. Backlight Characteristic

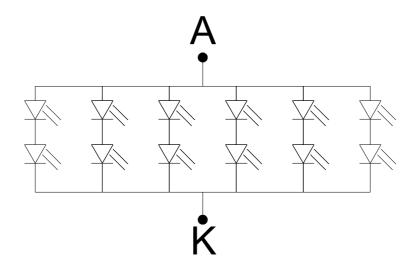
# 5.1. Backlight Characteristic

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	VF	Ta=25 °C, I <sub>F</sub> =20mA/LED	11.0	12.0	13.0	V
Forward Current	lF	Ta=25 °C, V <sub>F</sub> =6V/LED		120		mA
Power Dissipation	PD		-	1440	-	mW
Uniformity	Avg		70	80	-	%
LED Lifetime		Ta=25 °C	20000	30000	ı	Hrs
Drive Method	Constant Current					
LED Configuration	12 V	Vhite LEDs (2 LEDs in one	string an	d 6 group	s in para	ıllel)

Note1: LED life time defined as follows: The final brightness is at 50% of original brightness.

The environmental conducted under ambient air flow, at Ta=25±2 °C, 60%RH±5%, I<sub>F</sub>=20mA

# 5.2. Backlight Characteristic



# Circuit Diagram:

Double Core Lamp

# 6. Optical Characteristics

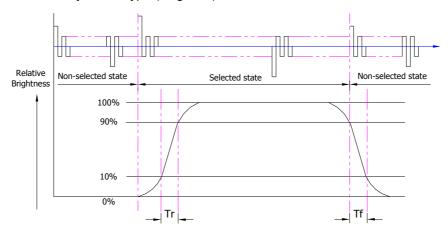
# 6.1. Optical Characteristics

Ta=25°C, VCI=3.3V, TN LC+ Polarizer

	Item		Cymbal	Condition	S	pecification	on	Unit
			Symbol	Condition	Min.	Тур.	Max.	Unit
	Luminance on							
	$TFT(I_f\!=\!20r$	mA/LED)	Lv	Normally	560	700	-	cd/m²
ode	Contrast Ratio	(See 6.3)	CR	viewing angle	700	900	-	
Backlight On (Transmissive Mode)	Response Time (See 6.2)		TR+TF	$\theta x = \phi Y = 0^{\circ}$	-	25	35	ms
mis		Red	XR			TBD		
ans		Reu	YR			TBD		
Ë	Ob was as a tilaitus	Green	XG			TBD		
o	Chromaticity Transmissive	Oreen	YG			TBD		
jht	(See 6.5)	Blue	Хв			TBD		
<del> </del>	(366 0.3)	DidC	ΥB			TBD		
3ac		White	Xw			TBD		
		vvriite	Yw			TBD		
		Horizontal	θх+		70	80	-	
	Viewing Angle	TIONZONIA	θх-	Center CR≥10	70	80	-	Dog
	(See 6.4)	Vertical	φY+	Center CR210	70	80	-	Deg.
		vertical	φY-		70	80	-	
	NTSC Ratio	(Gamut)			-	60	-	%

# 6.2. Definition of Response Time

# 6.2.1. Normally Black Type (Negative)



Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

# Relative Brightness Non-selected state 100% 90%

#### 6.2.2. Normally White Type (Positive)

10%

Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf -

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

\_ Tr

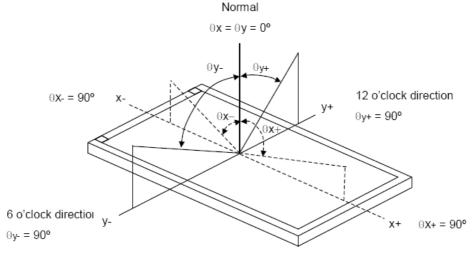
#### 6.3. Definition of Contrast Ratio

Contrast is measured perpendicular to display surface in reflective and transmissive mode. The measurement condition is:

Measuring Equipment	Eldim or Equivalent
Measuring Point Diameter	3mm//1mm
Measuring Point Location	Active Area centre point
Toot pottorn	A: All Pixels white
Test pattern	B: All Pixel black
Contrast setting	Maximum

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

# 6.4. Definition of Viewing Angles

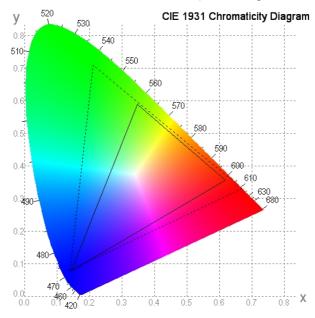


Measuring machine: LCD-5100 or EQUI

#### 6.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)

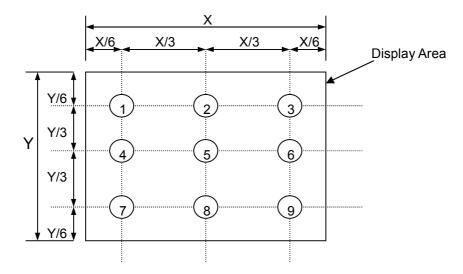


## 6.6. Definition of Surface Luminance, Uniformity and Transmittance

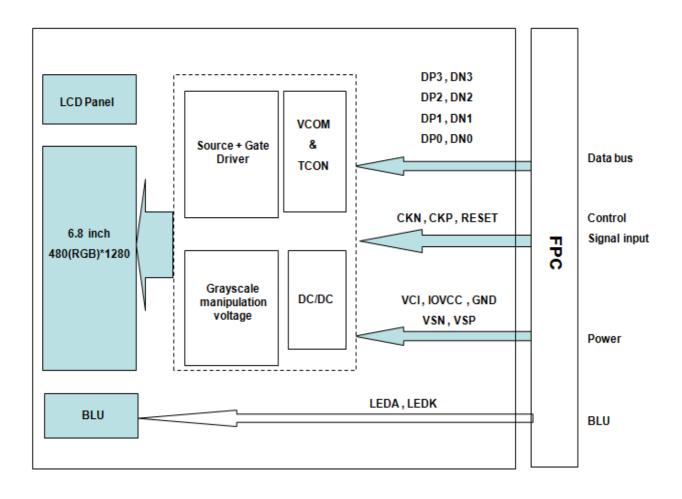
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

- 6.6.1. Surface Luminance:  $L_V$  = average ( $L_{P1}$ : $L_{P9}$ )
- 6.6.2. Uniformity = Minimal  $(L_{P1}:L_{P9})$  / Maximal  $(L_{P1}:L_{P9})$  \* 100%
- 6.6.3. Transmittance =  $L_V$  on LCD /  $L_V$  on Backlight \* 100%

Note: Measuring machine: BM-7



# 7. Block Diagram and Power Supply



# 8. Interface Pins Definition

No.	Symbol	Function	Remark
1	GND	Ground	
2	VCI	A power supply for DC/DC circuit	
3	VCI	A power supply for DC/DC circuit	
4	IOVCC	A power supply for the I/O circuit	
5	GND	Ground	
6	RESET	Reset pin	
7	TE	No connection	
8	GND	Ground	
9	GND	Ground	
10	DN3	MIPI data Input	
11	DP3	MIPI data Input	
12	GND	Ground	
13	DN2	MIPI data Input	
14	DP2	MIPI data Input	
15	GND	Ground	
16	CKN	MIPI clock Input	
17	CKP	MIPI clock Input	
18	GND	Ground	
19	DN1	MIPI data Input	
20	DP1	MIPI data Input	
21	GND	Ground	
22	DN0	MIPI data Input	
23	DP0	MIPI data Input	
24	GND	Ground	
25	VSP	Input voltage from the set-up circuit (4.5V to 6.0V)	
26	VSN	Input voltage from the set-up circuit (-4.5V to -6.0V).	
27	LEDK	Led cathode	
28	LEDK	Led cathode	
29	LEDA	Led anode	
30	LEDA	Led anode	

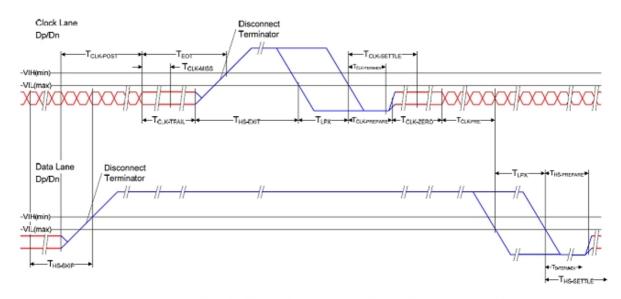
# 9. AC Characteristics

# 9.1. MIPI Input timing

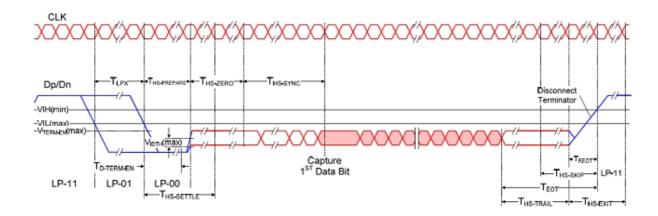
For 480RGBx1280

:	Cumbal		Value		Unit
	Symbol	Min.	Тур.	Max.	Offic
MIPI (4 Lane) @Frame rate=60Hz			386		Mbps
Lane) @Frame rate=60Hz			515		Mbps
DCLK frequency @Frame rate=60Hz	Focik		64.4		MHz
HSYNC period time	Тн		824		DCLK
Horizontal display area	Тно	480			DCLK
HSYNC pulse width	THPW		24	-	DCLK
HSYNC back porch	Тнвр		160	-	DCLK
HSYNC front porch	Тғар		160	-	DCLK
VSYNC period time	Tv		1304		Н
Vertical display area	Tvo		1280		Н
VSYNC pulse width	Tvpw		2	-	Н
VSYNC back porch	Tvap		10	-	Н
VSYNC front porch	TVFP		12	-	Н

# 9.2. MIPI AC characteristics



Switching the clock lane between clock transmission and low-power mode



Timing of high-speed data transmission in bursts

Parameter	Donori nt	Spec.			
Parameter	Descript	Min.	Тур.	Max.	Unit
T <sub>REOT</sub>	30%-85% rise time and fall time	-	-	35	ns
T <sub>CLK-MISS</sub>	Timeout for receiver to detect absence of Clock transitions and disable the Clock Lane HS-RX.	-	-	60	ns
T <sub>CLK-POST</sub> *1	Time that the transmitter continues to send HS dock after the last associated Data Lane has transitioned to LP Mode. Interval is defined as the period from the end of The-transmit to the beginning of Tolk-transmit.	60 ns + 52*UI (For DCS)	-		ns
T <sub>CLK-PRE</sub>	Time that the HS clock shall be driven by the transmitter prior to any associated Data Lane beginning the transition from LP to HS mode.	8	-		ns
T <sub>CLK-SETTLE</sub>	Time interval during which the HS receiver shall ignore any Clock Lane HS transitions, starting from the beginning of Tolk-PRE.	95	-	300	ns
T <sub>CLK-TERM-EN</sub>	Time for the Clock Lane receiver to enable the HS line termination, starting from the time point when Dn crosses V <sub>L,MAX</sub> .	Time for Dn to reach VTERM-EN	-	38	ns
T <sub>HS-SETTLE</sub>	Time interval during which the HS receiver shall ignore any Data Lane HS transitions, starting from the beginning of Theorem.	85 ns + 6*UI	-	145 ns + 10*UI	ns
T <sub>EOT</sub>	Time from start of $T_{HS-TRAIL}$ or $T_{CLK-TRAIL}$ period to start of LP-11 state	-	-	105ns+48*UI	-

T <sub>HS-EXIT</sub> <sup>(1)</sup>	time to drive LP-11 after HS burst	100			ns	
T <sub>HS-PREPARE</sub>	Time to drive LP-00 to prepare for HS transmission	40ns + 4*UI	-	- 85ns+6*UI		
T <sub>HS-PREPARE</sub> + T <sub>HS-ZERO</sub>	T <sub>HS-PREPARE</sub> + Time to drive HS-0 before the Sync sequence	PARE + Time to drive HS-0 before the Sync sequence 145ns + 10*UI		-	ns	
T <sub>HS-SKIP</sub>	Time-out at RX to ignore transition period of EoT	40	-	55ns+4*UI	ns	
T <sub>HS-TRAIL</sub>	Time to drive flipped differential state after last payload data bit of a HS transmission burst	60 + <b>4</b> *UI	-	-	ns	
T <sub>LPX</sub>	Length of any Low-Power state period	50	-	-	ns	
Ratio T <sub>LPX</sub>	Ratio of $T_{LPX(MASTER)}/T_{LPS(SLAVE)}$ between Master and Slave side	2/3	-	3/2	-	
T <sub>TA-GET</sub>	Time to drive LP-00 by new TX	5*T <sub>LPX</sub>		ns		
T <sub>TA-GO</sub>	Time to drive LP-00 after Turnaround Request	4*T <sub>LPX</sub>		ns		
T <sub>TA-SURE</sub>	Time-out before new TX side starts driving	$T_{LPX}$	-	2*T <sub>LPX</sub>	ns	

## Note: (1) For image transmission:

Tclk-postmin value =164 when MIPI max frequency per lane = 0.53Gbps.

TCLK-POSTMIN value =112 when MIPI max frequency per lane = 1Gbps

# 10. Reset Timing

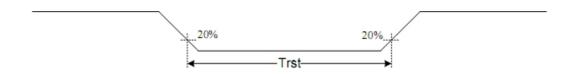
When RESETB of the reset pin equals to Low, it will be in the condition of reset. When it is in the condition of reset, it will make the device recover the initial set.

However, in order to avoid the reset noise cause reset, there is a mechanism to judge about whether the reset is needed or not.

The closed interval of Low can be shown as the following.

(Test condition: VDDIO=1.65V~3.6V, VSS=0V, TA=-20 ~+85)

Parameter	Symbol	Conditions	Spec.			I I m i A
			Min.	Тур.	Max	Unit
Reset low pulse width	Trst		20	-	•	μs



# 11. Quality Assurance

## 11.1. Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

#### 11.2. Standard for Quality Test

11.2.1 Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

11.2.2 Sampling Criteria:

Visual inspection: AQL 1.5% Electrical functional: AQL 0.65%.

11.2.3 Reliability Test:

Detailed requirement refer to Reliability Test Specification.

# 11.3. Nonconforming Analysis & Disposition

- 11.3.1 Nonconforming analysis:
  - 11.3.1.1 Customer should provide overall information of non-conforming sample for their complaints.
  - 11.3.1.2 After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.
  - 11.3.1.3 If cannot finish the analysis on time, customer will be notified with the progress status.
- 11.3.2 Disposition of nonconforming:
  - 11.3.2.1 Non-conforming product over PPM level will be replaced.
  - 11.3.2.2 The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

# 11.4. Agreement Items

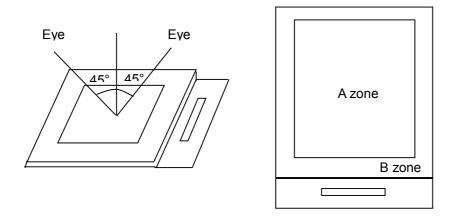
Shall negotiate with customer if the following situation occurs:

- 11.4.1 There is any discrepancy in standard of quality assurance.
- 11.4.2 Additional requirement to be added in product specification.
- 11.4.3 Any other special problem.

# 11.5. Standard of the Product Visual Inspection

# 11.5.1 Appearance inspection:

- 11.5.1.1 The inspection must be under illumination about  $1000 1500 \, lx$ , and the distance of view must be at  $30 cm \pm 2 cm$ .
- 11.5.1.2 The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.
- 11.5.1.3 Definition of area: A Zone: Active Area, B Zone: Viewing Area,



# 11.5.2 Basic principle:

- 11.5.2.1 A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.
- 11.5.2.2 New item must be added on time when it is necessary.

# 11.6. Inspection Specification

No.	Item	Criteria (Unit: mm)		
01	Black / White spot Foreign material (Round type) Pinholes Stain	a b	Area Size  φ≤0.20  0.20<φ≤0.50  0.50<φ	Acc. Qty Ignore N≤3 0
	Particles inside cell. (Minor defect)	φ= (a + b) /2 Distance between 2 defe	ects should more than 3n	nm apart.

			Display Area	Total		
		Bright dot	N≤2	N≤2	Note1	
		Dark dot	N≤4	N≤4	Note	
02	Electrical Defect	Total dot	N≤4	N≤4		
02	(Minor defect)	Mura Not visible throu		5% ND filters.	Note 2	
	· .	Remark:  1. Bright dot caused	d by scratch and foreign	object accords	to item 1.	
03	Black and White line Scratch Foreign material (Line type) (Minor defect)	Length / L ≤ 2.5 L ≤ 2.5 /	$\begin{array}{c} \text{Width} \\ \text{W} \leq 0.03 \\ 0.03 < \text{W} \leq 0.05 \\ 0.05 < \text{W} \leq 0.10 \\ 0.1 < \text{W} \\ \text{Total} \\ \end{array}$	Acc. Qty Ignore 3 2 0 3		
		Distance between 2 defects should more than 3mm apart. Scratches not viewable through the back of the display are acceptable.				
04	Glass Crack (Minor defect)	Crack is potential to enlarge, any type is not allowed.				

	Glass Chipping Pad Area: (Minor defect)		
		Length and Width	Acc. Qty
		c > 3.0, b< 1.0	1
05		c< 3.0, b< 1.0	3
		a <glass td="" thick<=""><td>kness</td></glass>	kness
	b va		
	Glass Chipping Rear of Pad Area: (Minor defect)		
		Length and Width	Acc. Qty
06		c > 3.0, b< 1.0	1
06		c< 3.0, b< 1.0	2
		c< 3.0, b< 0.5	4
	h c	a <glass td="" thick<=""><td>ness</td></glass>	ness
	Glass Chipping Except Pad Area: (Minor defect)	Length and Width	Acc. Qty
		c > 3.0, b< 1.0	1
07		c< 3.0, b< 1.0	2
	b A	c< 3.0, b< 0.5	4
	a A	a <glass td="" thick<=""><td>kness</td></glass>	kness
	Glass Corner Chipping:		
(Minor defect)	(Willion delect)	Length and Width	Acc. Qty
		c < 3.0, b< 3.0	Ignore
80		a <glass td="" thick<=""><td>ness</td></glass>	ness
	b a c		

	Glass Burr:					
	(Minor defect)					
				Leng	th	Acc. Qty
				F < 1	.0	Ignore
09				s burr don't nsion.	affect ass	semble and module
10	FPC Defect: (Minor defect)  a w a	_ ←	(w: c	Dent, pinhole ircuitry width.) Open circuit i No oxidation,	) s unaccept	
			D:	,		_
				meter	Acc. Qt	
11	Bubble on Polarizer	<u> </u>		£0.20	Ignore	<u>;                                    </u>
''	(Minor defect)	<u> </u>		<φ≤0.30	4	
		<u> </u>		<φ≤0.50	Nama	
			0.5	i0 < φ	None	
	Dent on Polarizer (Minor defect)			meter	Acc. Qt	
12				£0.20	Ignore	<u>:</u>
				<φ≤0.30	4	
				<φ≤0.50	1	
			0.5	50 < φ	None	
13	Bezel	13.1 No rust, distort			ner contam	ination.

		D: Diameter W: width L: length
		14.1 Spot: D<0.25 is acceptable
		0.25≤D≤0.4
		2dots are acceptable and the distance between defects should more
		than 10 mm.
14	Touch Panel	D>0.4 is unacceptable
		14.2 Dent: D>0.40 is unacceptable
		14.3 Scratch: W≤0.03, L≤10 is acceptable,
		0.03 <w⊴0.10, acceptable<="" is="" l≤10="" td=""></w⊴0.10,>
		Distance between 2 defects should more than 10 mm.
		W>0.10 is unacceptable.
		15.1 No distortion or contamination on PCB terminals.
		15.2 All components on PCB must same as documented on the
15	PCB	BOM/component layout.
		15.3 Follow IPC-A-600F.
		15.3 FOIIOW IPC-A-000F.
16	Soldering	Follow IPC-A-610C standard
		The below defects must be rejected.
		17.1 Missing vertical / horizontal segment,
	Electrical Defect (Major defect)	17.2 Abnormal Display.
		17.3 No function or no display.
17		17.4 Current exceeds product specifications.
		17.5 LCD viewing angle defect.
		17.6 No Backlight.
		17.7 Dark Backlight.
		17.8 Touch Panel no function.

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

#### 11.7. Classification of Defects

- 11.7.1 Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 11.7.2 Two minor defects are equal to one major in lot sampling inspection.

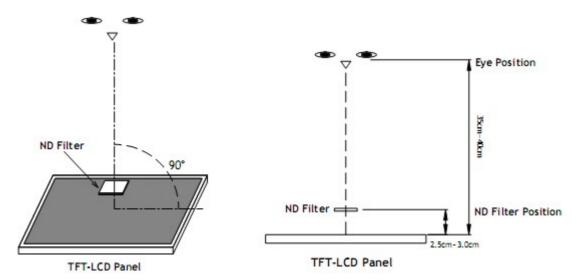
# 11.8. Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

# 11.9. Packaging

- 11.9.1 There should be no damage of the outside carton box, each packaging box should have one identical label.
- 11.9.2 Modules inside package box should have compliant mark.
- 11.9.3 All direct package materials shall offer ESD protection

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is  $350 \text{mm} \pm 50 \text{mm}$ .

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is  $350 \text{mm} \pm 50 \text{mm}$ .

**Note2:** Mura on display which appears darker / brighter against background brightness on parts of display area.

# 12. Reliability Specification

No	ltem	Condition	Quantity	Criteria
1	High Temperature Operating	60°C, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20°C, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity	40°C, 90%RH, 96Hrs	2	GB/T2423.3 -2006
4	High Temperature Storage	65°C, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-20°C, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test	-20°C, 60min ~ 60°C, 60min, 20 cycles.	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X, Y, Z 30 min for each direction.	2	GB/T5170.14 -2009
8	Floatrical Static Discharge	Air: $\pm$ 4KV 150pF/330 $\Omega$ 5 times	2	GB/T17626.2
0	Electrical Static Discharge	Contact: $\pm$ 2KV 150pF/330 $\Omega$ 5 times		-2006
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	2	GB/T2423.8 -1995

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

# 13. Precautions and Warranty

#### 13.1 Safety

- 13.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 13.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

# 13.2. Handling

- 13.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 13.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

#### 13.3. Storage

13.3.1 Do not store the LCD module beyond the specified temperature ranges.

## 13.4. Metal Pin (Apply to Products with Metal Pins)

13.4.1. Pins of LCD and Backlight

13.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering

13.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

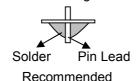
Maximum Solder Temperature: 370 ℃

Maximum Solder Time: 3s at the maximum temperature

Recommended Soldering Temp: 350±20 ℃

Typical Soldering Time: ≤3s

13.4.1.3. Solder Wetting



Solder Pin Lead
Not Recommended

13.4.2. Pins of EL

13.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.

13.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.

13.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270°C~290°C

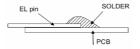
Typical Soldering Time: ≤2s

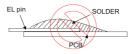
Minimum solder distance from EL lamp (body):2.0mm

13.4.2.4. No horizontal press on the EL leads during soldering.

13.4.2.5. 180° bend EL leads three times is not allowed.

#### 13.4.2.6. Solder Wetting





Recommended

Not Recommended

13.4.2.7. The type of the solder iron:





Recommended

Not Recommended

13.4.2.8. Solder Pad



#### 13.5. Operation

- 13.5.1. Do not drive LCD with DC voltage
- 13.5.2. Response time will increase below lower temperature
- 13.5.3. Display may change color with different temperature
- 13.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear "fractured".

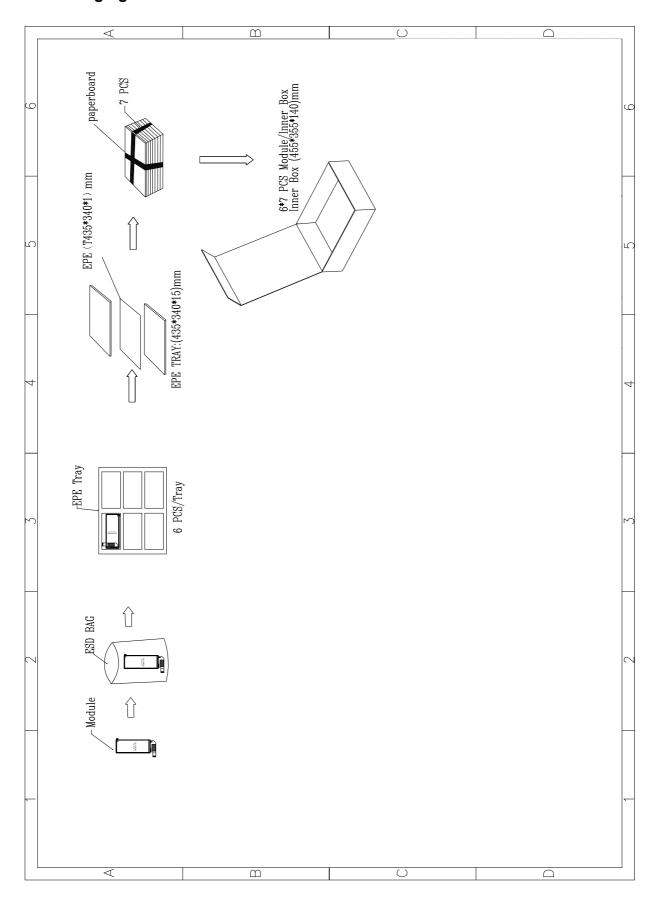
#### 13.6. Static Electricity

- 13.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 13.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 13.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

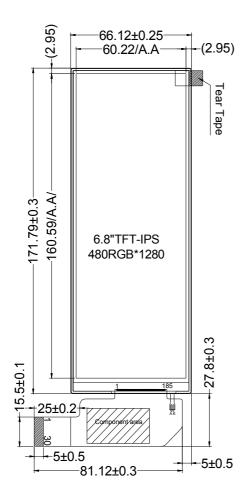
## 13.7. Limited Warranty

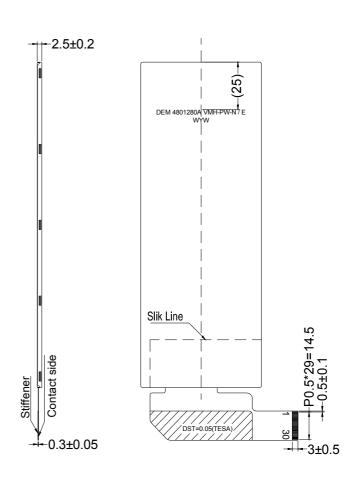
- 13.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 13.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.
- 13.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

# 14. Packaging



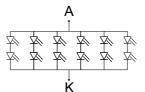
# 15. Outline Drawing





#### NOTES:

- 1.Display size:6.8"TFT
- 2. Viewing direction: FULL VIEW/IPS
- 3. Display mode: Transmissive/Normal Black
- 4.Operation temperature:-20°C~+60°C
- 5.Storage temperature:-20°C~+65°C
- 6.Driver IC:EK79030
- 7.Power supply voltage:3.3V
- 8.Backlight: White(12 LED)/12V(TYP)/120mA
- 9.ROHS must be complied
- \* Unspecification tolerance are  $\pm$ 0.2mm



Circuit Diagram: Double Core Lamp

PIN	SYMBO
1	GND
2	VCI
3	VCI
4	IOVCC
5	GND
6	RESET
7	TE
8	GND
9	GND
10	DN3
11	DP3
12	GND
13	DN2
14	DP2
15	GND
16	CKN
17	CKP
18	GND
19	DN1
20	DP1
21	GND
22	DN0
23	DP0
24	GND
25	VSP
26	VSN
27	LEDK
28	LEDK
29	LEDA
30	LEDA